FAIRCHILD SEMICONDUCTOR™

February 1992
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74LVQ174
Low Voltage Hex D-Type Flip-Flop with Master Reset

General Description

The LVQ174 is a high-speed hex D-type flip-flop. The device is used primarily as a 6-bit edge-triggered storage register. The information on the D inputs is transferred to storage during the LOW-to-HIGH clock transition. The device has a Master Reset to simultaneously clear all flip-flops.

Features

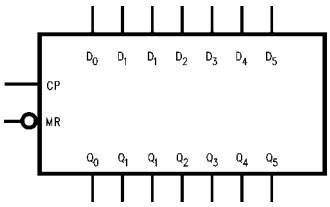
- Ideal for low power/low noise 3.3V applications
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Guaranteed pin-to-pin skew AC performance
- Guaranteed incident wave switching into 75Ω

Ordering Code:

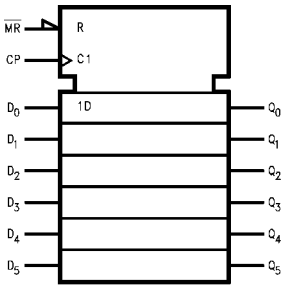
Order Number	Package Number	Package Description
74LVQ174SC	M16A	16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74LVQ174SJ	M16D	16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

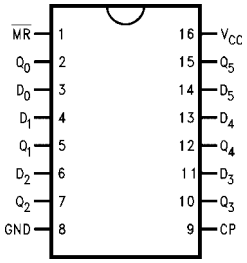
Logic Symbols



IEEE/IEC



Connection Diagram



Pin Descriptions

Pin Names	Description
D_0–D_5	Data Inputs
CP	Clock Pulse Input
$\overline{MR}$	Master Reset Input
Q_0–Q_5	Outputs

Functional Description

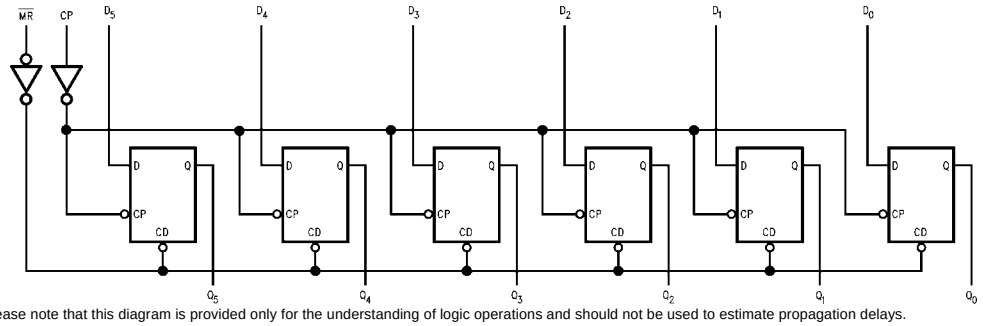
The LVQ174 consists of six edge-triggered D-type flip-flops with individual D inputs and Q outputs. The Clock (CP) and Master Reset ($\overline{MR}$) are common to all flip-flops. Each D input's state is transferred to the corresponding flip-flop's output following the LOW-to-HIGH Clock (CP) transition. A LOW input to the Master Reset ($\overline{MR}$) will force all outputs LOW independent of Clock or Data inputs. The LVQ174 is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

Truth Table

Inputs			Output
$\overline{MR}$	CP	D	Q
L	X	X	L
H	⌐	H	H
H	⌐	L	L
H	L	X	Q

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
⌐ = LOW-to-HIGH Transition

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

Supply Voltage (V_{CC})	−0.5V to +7.0V
DC Input Diode Current (I_{IK})	
V_I = −0.5V	−20 mA
V_I = V_{CC} + 0.5V	+20 mA
DC Input Voltage (V_I)	−0.5V to V_{CC} + 0.5V
DC Output Diode Current (I_{OK})	
V_O = −0.5V	−20 mA
V_O = V_{CC} + 0.5V	+20 mA
DC Output Voltage (V_O)	−0.5V to V_{CC} + 0.5V
DC Output Source or Sink Current (I_O)	±50 mA
DC V_{CC} or Ground Current (I_{CC} or I_{GND})	±200 mA
Storage Temperature (T_{STG})	−65°C to +150°C
DC Latch-Up Source or Sink Current	±100 mA

Recommended Operating Conditions (Note 2)

Supply Voltage (V_{CC})	2.0V to 3.6V
Input Voltage (V_I)	0V to V_{CC}
Output Voltage (V_O)	0V to V_{CC}
Operating Temperature (T_A)	−40°C to +85°C
Minimum Input Edge Rate (ΔV/Δt)	
V_{IN} from 0.8V to 2.0V	
V_{CC} @ 3.0V	125 mV/ns

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	T_A = +25°C	T_A = −40°C to +85°C		Units	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.0	2.0	V	V_{OUT} = 0.1V or V_{CC} − 0.1V
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.8	0.8	V	V_{OUT} = 0.1V or V_{CC} − 0.1V
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	I_{OUT} = −50 μA
		3.0		2.58	2.48	V	V_{IN} = V_{IL} or V_{IH} (Note 3) I_{OH} = −12 mA
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	I_{OUT} = 50 μA
		3.0		0.36	0.44	V	V_{IN} = V_{IL} or V_{IH} (Note 3) I_{OL} = 12 mA
I_{IN}	Maximum Input Leakage Current	3.6		±0.1	±1.0	μA	V_I = V_{CC}, GND
I_{OLD}	Minimum Dynamic (Note 4) Output Current	3.6			36	mA	V_{OLD} = 0.8V Max (Note 5)
I_{OHD}		3.6			−25	mA	V_{OHD} = 2.0V Min (Note 5)
I_{CC}	Maximum Quiescent Supply Current	3.6		4.0	40.0	μA	V_{IN} = V_{CC} or GND
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	3.3	0.7	0.8		V	(Note 6)(Note 7)
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	3.3	−0.6	−0.8		V	(Note 6)(Note 7)
V_{IHD}	Maximum High Level Dynamic Input Voltage	3.3	1.8	2.0		V	(Note 6)(Note 8)
V_{ILD}	Maximum Low Level Dynamic Input Voltage	3.3	1.6	0.8		V	(Note 6)(Note 8)

Note 3: All outputs loaded; thresholds on input associated with output under test.

Note 4: Maximum test duration 2.0 ms, one output loaded at a time.

Note 5: Incident wave switching on transmission lines with impedances as low as 75Ω for commercial temperature range is guaranteed.

Note 6: Worst case package.

Note 7: Max number of outputs defined as (n). Data inputs are driven 0V to 3.3V; one output at GND.

Note 8: Max number of Data Inputs (n) switching. (n − 1) inputs switching 0V to 3.3V. Input-under-test switching: 3.3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}), f = 1 MHz.

AC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	$T_A = +25°C$, $C_L = 50$ pF			$T_A = -40°C$ to $+85°C$, $C_L = 50$ pF		Units
			Min	Typ	Max	Min	Max	
f_{MAX}	Maximum Clock Frequency	2.7	60	90		50		MHz
		3.3 ± 0.3	90	100		70		
t_{PLH}	Propagation Delay CP to Q_n	2.7	2.0	10.8	16.2	1.5	18.0	ns
		3.3 ± 0.3	2.0	9.0	11.5	1.5	12.5	
t_{PHL}	Propagation Delay CP to Q_n	2.7	2.0	10.2	15.5	1.5	17.0	ns
		3.3 ± 0.3	2.0	8.5	11.0	1.5	12.0	
t_{PHL}	Propagation Delay $\overline{MR}$ to Q_n	2.7	2.5	10.8	16.2	2.0	18.0	ns
		3.3 ± 0.3	2.5	9.0	11.5	2.0	12.5	
t_{OSHL}, t_{OSLH}	Output to Output Skew (Note 9)	2.7		1.0	1.5		1.5	ns
		3.3 ± 0.3		1.0	1.5		1.5	

Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}). Parameter guaranteed by design.

AC Operating Requirements

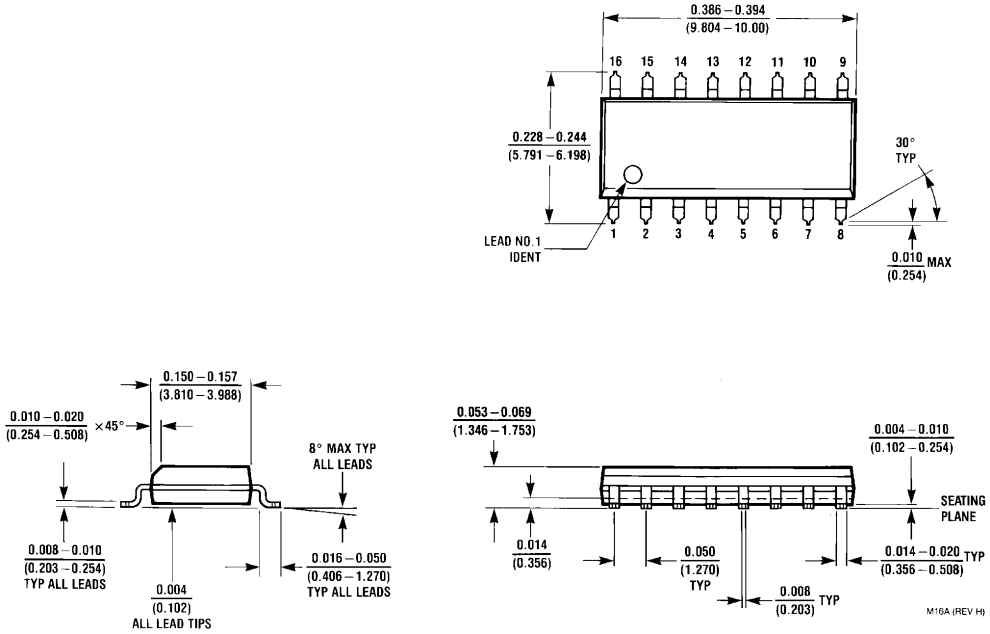
Symbol	Parameter	V_{CC} (V)	$T_A = +25°C$, $C_L = 50$ pF		$T_A = -40°C$ to $+85°C$, $C_L = 50$ pF	Units
			Typ	Guaranteed Minimum		
t_S	Setup Time, HIGH or LOW D_n to CP	2.7	3.0	8.0	10.0	ns
		3.3 ± 0.3	2.5	6.5	7.0	
t_H	Hold Time, HIGH or LOW D_n to CP	2.7	1.2	4.0	4.5	ns
		3.3 ± 0.3	1.0	3.0	3.0	
t_W	$\overline{MR}$ Pulse Width, LOW	2.7	1.2	7.0	10.0	ns
		3.3 ± 0.3	1.0	5.5	7.0	
t_W	CP Pulse Width	2.7	1.2	7.0	10.0	ns
		3.3 ± 0.3	1.0	5.5	7.0	
t_{REC}	Recovery Time $\overline{MR}$ to CP	2.7	0	3.5	3.5	ns
		3.3 ± 0.3	0	2.5	2.5	

Capacitance

Symbol	Parameter	Typ	Units	Conditions
C_{IN}	Input Capacitance	4.5	pF	V_{CC} = Open
C_{PD} (Note 10)	Power Dissipation Capacitance	23	pF	V_{CC} = 3.3V

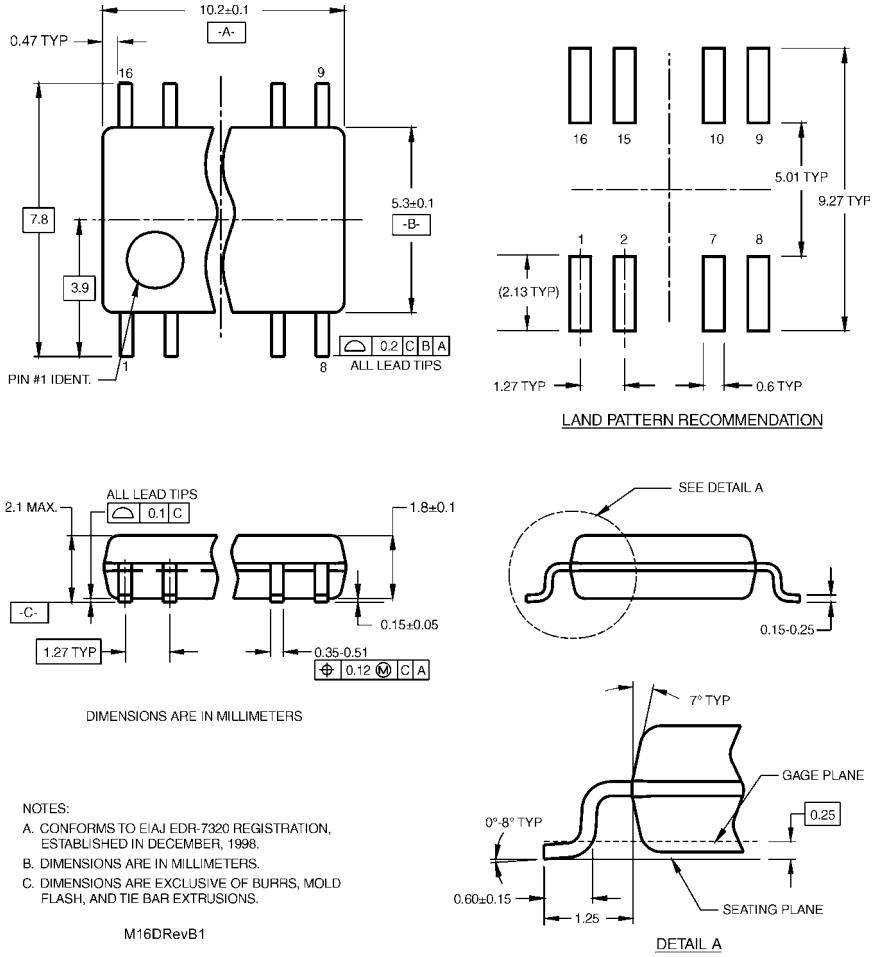
Note 10: C_{PD} is measured at 10 MHz.

Physical Dimensions inches (millimeters) unless otherwise noted



16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
Package Number M16A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



NOTES:

A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.

B. DIMENSIONS ARE IN MILLIMETERS.

C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M16DRevB1

16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M16D

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